

## CMCM

### Ceramic Multi-Chip Module Package (CMCM)

The MCM/CBGA and MCM/PBGA by Amkor Technology incorporates the latest technology in high-density Ceramic and Plastic IC packaging. The high-speed performance and thermal advantages of the CBGA and PBGA package provide the platform for increased enhancement for mixed semiconductor technologies such as: Analog/Digital, bipolar/CMOS, ASIC, DSP, etc. in a single IC package.

#### Applications:

This MCM technology allows existing and presently available ICs to be designed in a single, space-saving, low-cost system package. MCM-CBGAs and MCM-PBGAs provide the features required by laptops, portables, sub-notebooks, telecomm, wireless, PC cards and other applications.

#### Features:

The MCM-CBGA offer a variety of features:

- Improved thermal performance
- Superior electrical performance
- Controlled impedance
- Very low design and tooling cost
- Electroless Au (gold) plating process
- Standard and custom ball counts available
- Eutectic solder balls
- Flexible circuit designs
- Advanced in-house design capability
- Versatile substrate routing
- Choice of package body sizes